



NPN PRE-BIASED (R1≠R2) SMALL SIGNAL IN DFN1006

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish - NiPdAu Solderable per MIL-STD-202,

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.0009 grams (Approximate)

Terminal Connections: See Marking Information

Product Summary

Part Number	R1 (NOM)	R2 (NOM)	Marking
DDTC123JLP	2.2kΩ	47kΩ	N0
DDTC143ZLP	4.7kΩ	47kΩ	N1
DDTC114YLP	10kΩ	47kΩ	N2

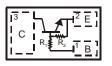
Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

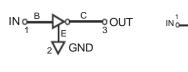
X1-DFN1006-3



Bottom View



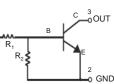
Package Pin Out Configuration



Mechanical Data

Method 208 @

Case: X1-DFN1006-3



Device Schematics

Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC123JLP-7	N0	7	8	3,000
DDTC143ZLP-7	N1	7	8	3,000
DDTC114YLP-7	N2	7	8	3,000
DDTC123JLP-7B	N0	7	8	10,000
DDTC143ZLP-7B	N1	7	8	10,000
DDTC114YLP-7B	N2	7	8	10,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

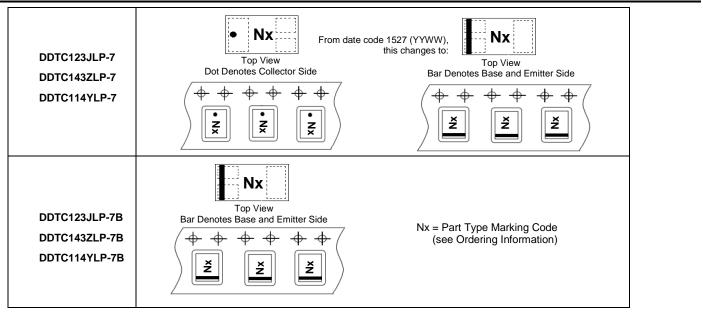
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	P/N	Symbol	Value	Unit	
Supply Voltage		Vcc	50	V	
	DDTC123JLP		-5 to +12		
Input Voltage	DDTC143ZLP	VIN	-5 to +30	V	
	DDTC114YLP		-5 to +40		
	DDTC123JLP		100		
Output Voltage	DDTC143ZLP	lo	100	mA	
	DDTC114YLP		70		
Maximum Collector Current		IC(MAX)	100	mA	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	250	mW
Power Deration above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ ext{ heta}JA}$	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

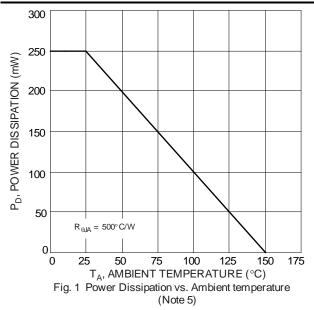
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	P/N	Symbol	Min	Тур	Max	Unit	Test Condition
Off Characteristics (Note 6)							
Collector-Base Breakdown Voltage		BV _{CBO}	50			V	$I_{\rm C} = 50 \mu A, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 7)		BV _{CEO}	50			V	$I_{\rm C} = 2mA, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage (Note	7)	BV _{EBO}	4.5			V	$I_{\rm E} = 50\mu A, I_{\rm C} = 0$
Collector Cutoff Current (Note 7)		ICEX	_		0.5	μA	$V_{CE} = 50V, V_{EB(OFF)} = 3.0V$
Base Cutoff Current (I _{BEX})		I _{BL}	_		0.5	μA	$V_{CE} = 50V, V_{EB(OFF)} = 3.0V$
Collector-Base Cut Off Current		I _{CBO}	_		0.5	μA	$V_{CB} = 50V, I_E = 0$
Collector-Emitter Cut Off Current, IO(OFF)	ICEO	_		0.5	μA	$V_{CE} = 50V, I_B = 0$
Emitter-Base Cut Off Current		I _{EBO}			0.5	mA	$V_{EB} = 5V, I_{C} = 0$
Input-Off Voltage		VI(OFF)	0.5			V	V _{CE} = 5V, I _C = 100µA
On Characteristics (Note 6)							• · · · ·
	DDTC123JLP		_		0.85		
Base-Emitter Turn-On Voltage (Note 7)	DDTC143ZLP	V _{BE(ON)}			0.85	V	$V_{CE} = 5V, I_C = 2mA$
	DDTC114YLP				0.95		
Base-Emitter Saturation Voltage (Note	DDTC123JLP				0.98		I _C = 10mA, I _B = 1mA
7)	DDTC143ZLP	(-)	_	—	0.998	V	
	DDTC114YLP			—	0.98		
Input-On Voltage		V _{I(ON)}		—	1.1	V	$V_0 = 0.3V, I_c = 5mA$
	DDTC123JLP	lı		—	7.2	mA	
Input Current	DDTC143ZLP		_		1.5		$V_1 = 5V$
	DDTC114YLP				7.2		<u> </u>
			50			—	$V_{CE} = 5V, I_C = 1mA$
			70			—	$V_{CE} = 5V, I_C = 2mA$
DC Current Gain		h _{FE}	125			—	$V_{CE} = 5V, I_C = 5mA$
			150		_	_	$V_{CE} = 5V, I_{C} = 10mA$
			180	—	—	—	$V_{CE} = 5V, I_{C} = 50mA$
Collector-Emitter Saturation Voltage		V _{CE(SAT)}	—	—	0.15	V	$I_{C} = 10mA, I_{B} = 1mA$
		VCE(SAT)	_	—	0.2	V	$I_{C} = 50 \text{mA}, I_{B} = 5 \text{mA}$
Output On Voltage (Same as V _{CE(SAT)})		V _{O(ON)}	_		0.3		$I_{\rm J} = 2.5 {\rm mA}, I_{\rm O} = 50 {\rm mA}$
Input Resistor +/-30%		∆R1	-30		30	%	
Resistor Ratio		∆ (R2/R1)	-20		-20	%	<u> </u>
Small Signal Characteristics		, , , , , , , , , , , , , , , , , , , ,		1		1	1
Transition Frequency (gain bandwidth product)		f⊤	—	250	—	MHz	$V_{CE} = 10V, I_E = 5mA, f = 100MHz$

5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
6. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.
7. Guaranteed by design. Notes:

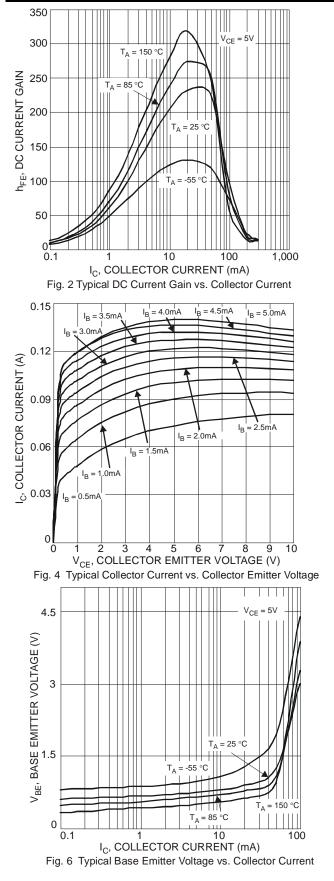


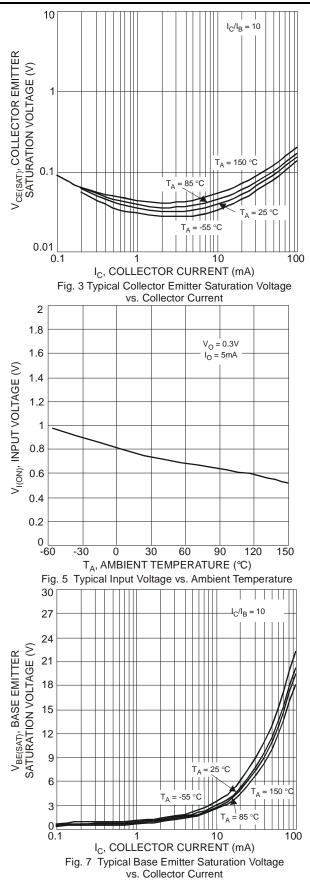
Derating Curve (@T_A = +25°C, unless otherwise specified.)





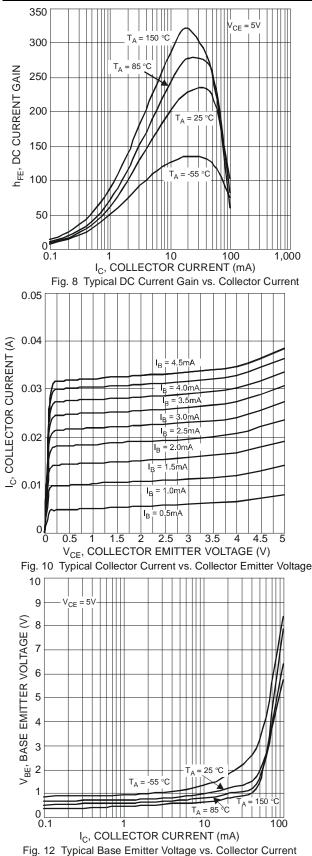
Typical Electrical Characteristics of DDTC123JLP (@T_A = +25°C, unless otherwise specified.)

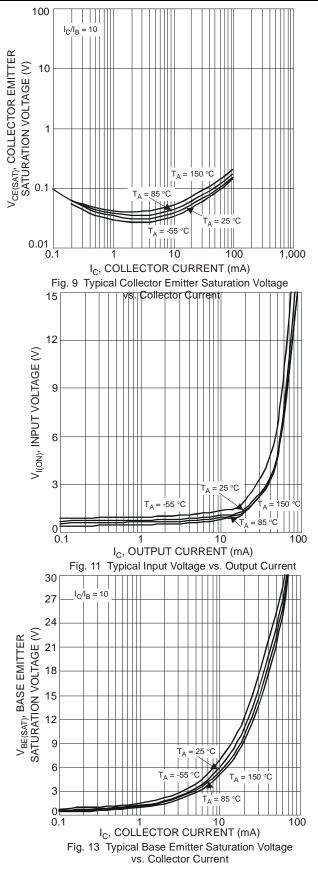






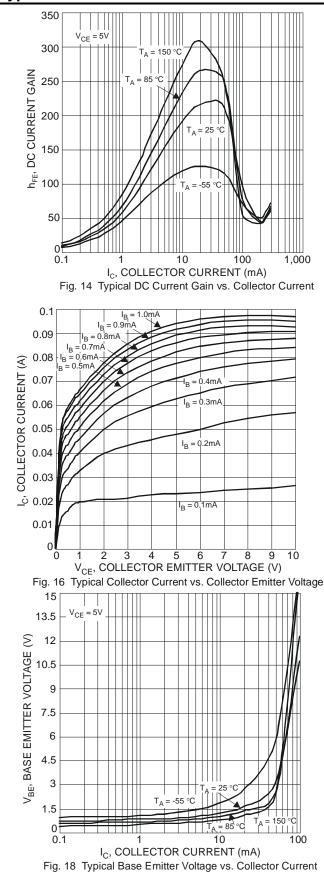
Typical Electrical Characteristics of DDTC143ZLP (@T_A = +25°C, unless otherwise specified.)

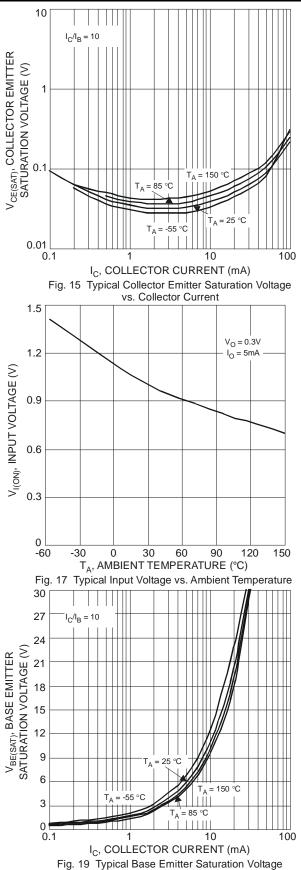






Typical Electrical Characteristics of DDTC114YLP (@T_A = +25°C, unless otherwise specified.)



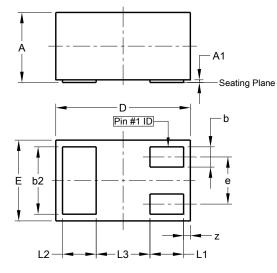


vs. Collector Current



Package Outline Dimensions

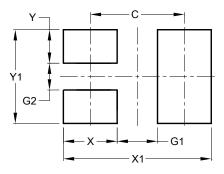
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
z	0.02	0.08	0.05		
All D	All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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